**Package information** 

# 1. Package summary

Terminal position code Q (quad)
Package type descriptive code PLCC52
Package type industry code PLCC52

Package style descriptive code PLCC (plastic leaded chip carrier)

Package style suffix code NA (not applicable)

Package body material typeP (plastic)IEC package outline code112E11JEDEC package outline codeMS-018JEITA package outline codeEDR-7319

Mounting method type S (surface mount)

**Issue date** 15-11-2001

#### **Table 1. Package summary**

Symbol	Parameter	Min	Тур	Nom	Max	Unit
D	package length	19.05	-	19.15	19.2	mm
E	package width	19.05	-	19.15	19.2	mm
Α	seated height	4.19	-	4.57	4.57	mm
A <sub>2</sub>	package height	[tbd]	-	3.86	[tbd]	mm
n <sub>2</sub>	actual quantity of termination	-	-	52	-	



plastic leaded chip carrier; 52 leads

### 2. Package outline

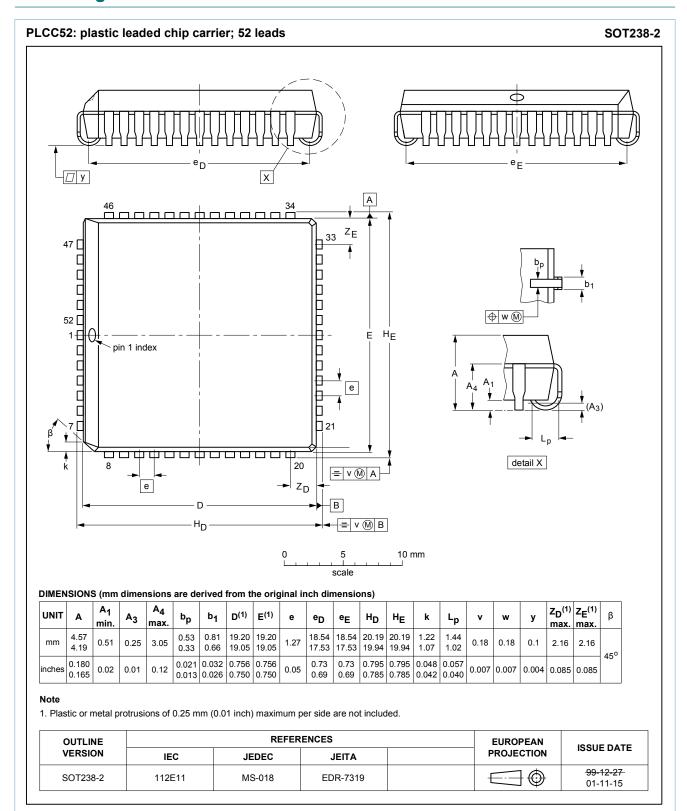
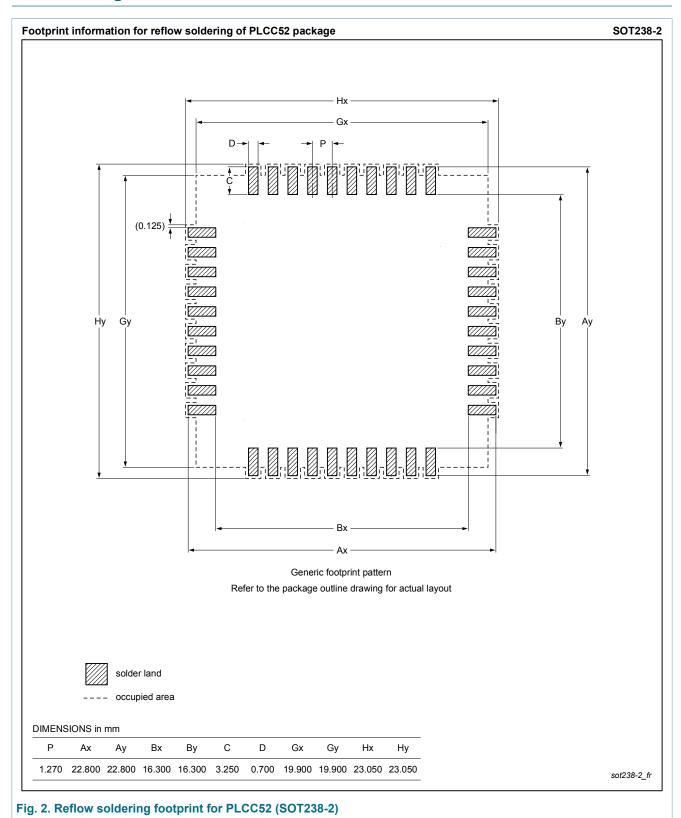


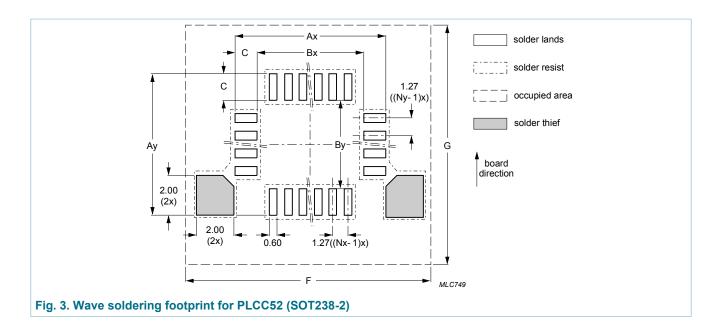
Fig. 1. Package outline PLCC52 (SOT238-2)

plastic leaded chip carrier; 52 leads

## 3. Soldering



#### plastic leaded chip carrier; 52 leads



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plastic leaded chip carrier; 52 leads

### 4. Legal information

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plastic leaded chip carrier; 52 leads

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